**ON Semiconductor** 

Is Now

# Onsemi

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# **200DPI High-Speed Contact** Image Sensor Module

# Description

The NOM02A6–AW49G contact image sensor (CIS) module integrates a white LED light source with reflector, lens and image sensor in a compact housing. The module is designed for document scanning, mark reading, gaming and office automation equipment applications and is suitable for scanning documents up to 104 mm wide. An analog video output achieves a scanning rate of 167 µsec/line. The NOM02A6–AW49G module employs proprietary CMOS image sensing technology from ON Semiconductor to achieve high–speed performance and high sensitivity.

# Features

- Light Source, Lens and Sensor are Integrated Into a Single Module
- 104 mm Scanning Width at 7.9 dots per mm Resolution
- 167 µsec/Line Scanning Speed @ 5.0 MHz Pixel Rate
- Analog Video Output
- Supports A6 Paper Size at up to 74 Pages per Minute
- White LED Light Source with Reflector
- Wide Dynamic Range
- Compact 119.7 mm x 19.0 mm x 13.7 mm Module Housing
- Low Power
- Light Weight 1.1 oz Packaging
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

# Applications

- Gaming, Ticket and Check Scanner Machines
- Receipt Scanners
- Mark Readers
- Office Automation Equipment

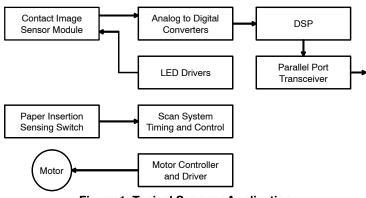


Figure 1. Typical Scanner Application



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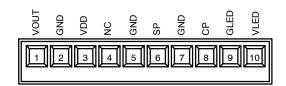


# IMAGE SENSOR MODULE A6 CASE MODAF

# MARKING DIAGRAM



# CONNECTOR PIN ASSIGNMENT



# **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

# Table 1. ORDERING INFORMATION

Part Number	Package	Shipping Configuration
NOM02A6-AW49G	(Pb-free)	100 per packing carton

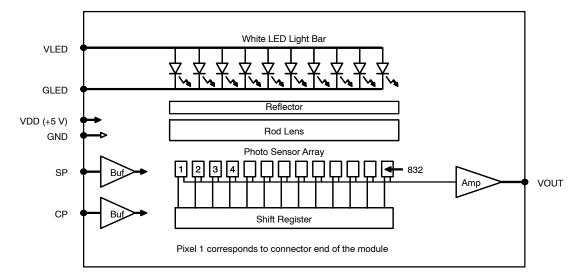


Figure 2. Simplified Block Diagram

# **Table 2. PIN FUNCTION DESCRIPTION**

Pin	Pin Name	Description
1	VOUT	Analog Video Output
2	GND	Ground
3	VDD	+5 V power supply
4	NC	Not connected
5	GND	Ground
6	SP	Shift register start pulse
7	GND	Ground
8	CP	Sampling clock pulse
9	GLED	Ground for the LED light source
10	VLED	Power supply for the LED light source

# **Table 3. ABSOLUTE MAXIMUM RATINGS**

Parameter	Symbol	Value	Unit
Power supply voltage	V <sub>DD</sub>	7	V
	V <sub>LED</sub>	6	V
Power supply current	I <sub>LED</sub>	350	mA
Input voltage range for SP, CP	V <sub>in</sub>	–0.5 to V <sub>DD</sub> + 0.5	V
Storage Temperature	T <sub>STG</sub>	-20 to 75	°C
Storage Humidity, Non-Condensing	H <sub>STG</sub>	10 to 90	%
ESD Capability, Contact Discharge (Note 1)	ESD <sub>HBM</sub>	±2	kV

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. This module assembly has been ESD tested to IEC61000-4-2 (HBM) Contact Discharge

# Table 4. RECOMMENDED OPERATING RANGES (Unless otherwise specified, these specifications apply T<sub>A</sub> = 25°C) (Note 2)

Parameter	Symbol	Min	Тур	Мах	Unit
Power supply voltage (Note 3)	V <sub>DD</sub>	4.5	5	5.5	V
	V <sub>LED</sub>	4.5	5	5.5	V
Power supply current	I <sub>DD</sub>	20	30	40	mA
	I <sub>LED</sub>	150	200	250	mA
Low level input voltage for SP, CP	V <sub>IL</sub>	0	0	0.8	V
High level input voltage for SP, CP	V <sub>IH</sub>	4.5	5.0	V <sub>DD</sub> + 0.3	V
Line scanning rate (Note 4)	T <sub>int</sub>	152	167	416	μs
Clock frequency (Note 5)	f	2.0	5.0	5.5	MHz
Clock period	t <sub>o</sub>	182	200	500	ns
Clock pulse width (Note 6)	t <sub>w</sub>	46	50	125	ns
Clock pulse high duty cycle	DC <sub>CP</sub>	20	25	60	%
Start pulse width (Note 6)	t <sub>wSP</sub>	150	180	480	ns
Start pulse setup time	t <sub>su</sub>	20			ns
Start pulse hold time	t <sub>h</sub>	20			ns
Prohibit crossing time (Note 7)	t <sub>prh</sub>	20			ns
Clock to Video output propagation delay rising	t <sub>pcor</sub>	115			ns
Clock to Video output propagation delay falling	t <sub>pcof</sub>	20			ns
Operating Temperature	T <sub>op</sub>	0		50	°C
Operating Humidity, Non-Condensing	H <sub>op</sub>	10		60	%

Refer to Figure 3 for more information on AC characteristics
 V<sub>LED</sub> directly affects illumination intensity, which directly affects V<sub>OUT</sub>.
 T<sub>int</sub> is the line scanning rate or integration time. T<sub>int</sub> is determined by the interval between two start pulses. The clock is proportional to T<sub>int</sub>.
 Main clock frequency (f) corresponds to the video sampling frequency.
 Min, Typ, Max specifications reflect operation at the corresponding Min, Typ, Max clock frequency.

Prohibit crossing time is to insure that two start pulses are not supplied in the same scan line time. SP may only be active high during one 7. falling edge of CP for any given scan.

# Table 5. PHYSICAL SPECIFICATIONS

Parameter	Symbol	Тур	Unit
Scan width	PDw	104	mm
Number of Photo Detector Arrays	PDA <sub>n</sub>	13	arrays
Number of Photo Detectors	PD <sub>n</sub>	832	elements

# Table 6. PHYSICAL CHARACTERISTICS

Parameter	Symbol	Min	Тур	Max	Unit
Pixel pitch	PD <sub>sp</sub>		125		μm
Inter-array spacing	PDA <sub>sp</sub>	150	180	210	μm
Inter-array vertical alignment	PDA <sub>vxp</sub>	-40	0	40	μm
White LED chromaticity coordinates	X Y	0.2 0.16	0.24 0.23	0.305 0.31	

# Table 7. ELECTRO-OPTICAL CHARACTERISTICS TEST CONDITIONS

Parameter	Symbol	Value	Unit
Power supply voltage	V <sub>DD</sub>	5.0	V
	V <sub>LED</sub>	5.0	V
Clock frequency	f	5.0	MHz
Clock pulse high duty cycle	DC <sub>CP</sub>	25	%
Line scanning rate	T <sub>int</sub>	167	μs
LED arrays pulsed time on (Note 8)	LED_Ton	26	ms
LED arrays pulsed time off (Note 8)	LED_Toff	356	ms
Operating Temperature	T <sub>op</sub>	25	°C

8. Production tested with pulsing LEDs.

Table 8. ELECTRO-OPTICAL CHARACTERISTICS (Unless otherwise specified, these specifications were achieved with the test conditions defined in Table 7)

Parameter	Symbol	Min	Тур	Max	Unit
Bright analog output voltage (Note 9)	V <sub>pavg</sub>	0.9	1.0	1.1	V
Bright output non-uniformity (Note 10)	Up	-30		30	%
Bright output non-uniformity total (Note 11)	U <sub>ptotal</sub>			60	%
Adjacent pixel non-uniformity (Note 12)	U <sub>padj</sub>			25	%
Dark output voltage (Note 13)	V <sub>d</sub>	150		350	mV
Dark non-uniformity (Note 14)	U <sub>d</sub>			50	mV
Modulation transfer function at 50 line pairs per in (lp/in) (Note 15)	MTF <sub>50</sub>	40			%
Modulation transfer function at 100 line pairs per in (lp/in) (Notes 15, 16)	MTF <sub>100</sub>	20			%

9.  $V_{pavg} = \Sigma V_{p(n)}/832$ , where  $V_p$  is the pixel amplitude value of  $V_{OUT}$  for a bright signal defined as a white document with LEDs turned on, n is the sequential pixel number in one scan line.

10. Up = [(Vpmax - Vpavg)/Vpavg] x 100%, or [Vpavg - Vpmin)/Vpavg] x 100%, whichever is greater, where Vpmax is the maximum pixel voltage of any pixel at full bright Vpmin is the minimum pixel voltage of any pixel at full bright

11. Uptotal =  $[(V_{pmax} - V_{pmin})/V_{pavg}] \times 100\%$ , 12. Upadj = MAX [ |  $(V_{p(n)} - V_{p(n+1)}) / V_{p(n)}$ ] x 100%, where Upadj is the nonuniformity in percent between adjacent pixels for a bright background

13. Vd is the pixel amplitude value of VOUT for a dark signal defined as a black document with LEDs turned off

 $14. U_d = V_{dmax} - V_{dmin}$ , where

 $V_{\text{dmax}}$  is the maximum pixel voltage of any dark pixel with the LEDs turned off

V<sub>dmin</sub> is the minimum pixel voltage of any dark pixel with the LEDs turned off

15.MTF = [(V<sub>max</sub> - V<sub>min</sub>)/(V<sub>max</sub> + V<sub>min</sub>)] x 100%, where V<sub>max</sub> is the maximum output voltage at the specified line pairs per inch (lp/in)

- Vmin is the minimum output voltage at the specified lp/in
- 16. For information only.

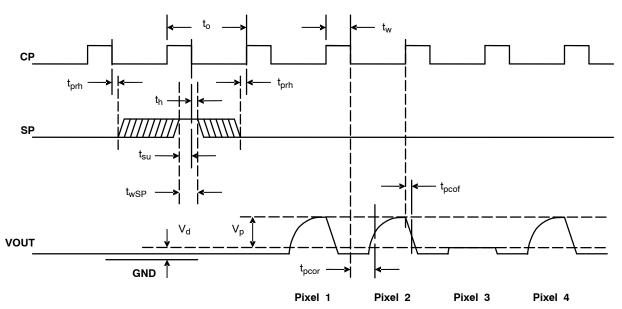


Figure 3. Timing Diagram

# **DESCRIPTION OF OPERATION**

# **Functional Description**

The NOM02A6–AW49G module consists of 13 contact image sensors, each with 64 pixel elements, that are cascaded to provide 832 photo–detectors with their associated multiplex switches and double–buffered digital shift register that controls its sequential readout. A buffer amplifies the video pixels from the image sensors and output the analog video signal of the module as shown in Figure 2. In operation, the sensors produce an analog image pixel signal (or video signal) proportional to the exposure on the corresponding picture elements on the document. The VOUT signal outputs 832 pixels for each scan line. The first bit shifted out from VOUT during each scan represents the first pixel on the connector end of the module.

A pictorial of the NOM02A6–AW49G cross section view is shown in Figure 4. Mounted in the module is a one–to–one graded–index micro lens array that focuses the scanned document image onto the sensing plane. Illumination is accomplished by means of an integrated LED light source. An internal reflector helps illuminate the document more completely, eliminating shadows caused by wrinkles in the paper. All components are housed in a small plastic housing, which has a glass cover. The top surface of the glass acts as the focal point for the object being scanned and protects the imaging array, micro lens assembly and LED light source from dust.

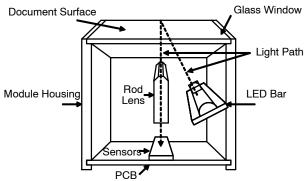


Figure 4. Module Cross Section View

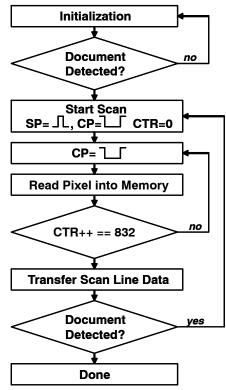
# **Connector Pin Out Description**

Connections to the module are via a 2.4x14.50mm 10-pin connector (ECE part number EBW-PK23-P010L2-3Z) located at one end of the module as shown in the package drawing on page 8. The location of pin number 1 is indicated on the package drawing.

### **Scanner Applications**

A typical use of the NOM02A6–AW49G module in scanner applications is shown in Figure 6. The document to be digitized is fed into the scanner where a sensor detects its presence. The scanner then operates the motor to move the paper under the contact image sensor module. The module illuminates the paper with internal LEDs and the image sensor pixel array detects the amount of reflected light and simultaneously measures a full line of pixels which are sampled and transferred to a FIFO for storage and conversion to a parallel output format. Once the pixel line is

processed, the motor advances the paper and the next scan line is captured.



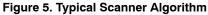


Figure 5 outlines the basic steps in the scanner control sequence. First the circuits are initialized and the scanner waits for a document to be detected, usually by a paper sensing switch. Then a start pulse and clock pulse are supplied to capture a line image. At the next clock pulse the first pixel value appears on the output. The pixel can be stored in a local line buffer memory. Subsequent clocks cause the remaining pixels to be shifted out and stored in the line buffer. Once the complete line has been shifted out it can be transferred to the host application and the system advances the paper and the line scan process repeats until the paper sensing switch indicates the document has passed completely through the scanner.

# **Device Marking and Barcode Description**

Each module is marked with a tag that contains the part number, a number combining the manufacturing date code and serial number and a barcode. The barcode presents the date code and serial number in Interleave 2 of 5 barcode format as follows

# YYMMSSSSSS

YY is the year,

where

MM is the month, and SSSSSS is the serial number.

# Glass Lens Care

Precautions should be taken to avoid scratching or touching the glass lens. The glass lens may be cleaned with alcohol.

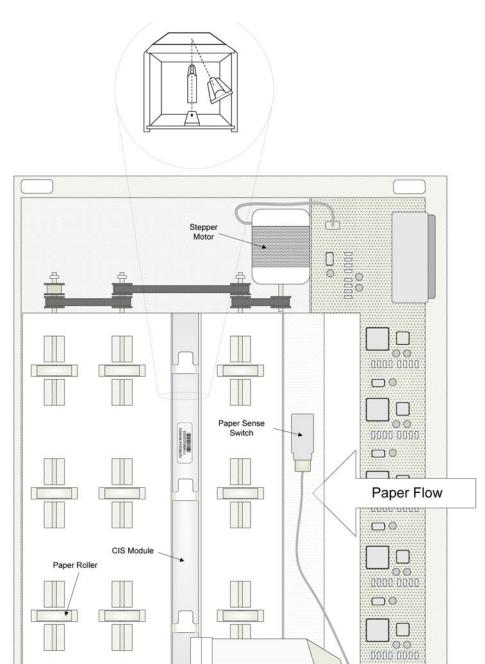


Figure 6. Typical Scanner Assembly

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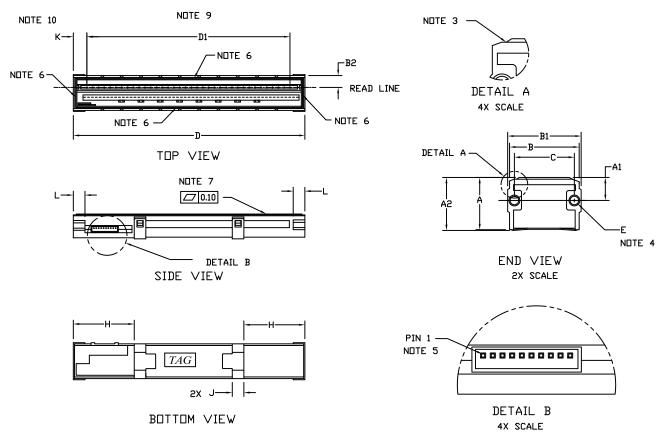
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# **PACKAGE DIMENSIONS**

# **IMAGE SENSOR MODULE A6** CASE MODAF **ISSUE O**



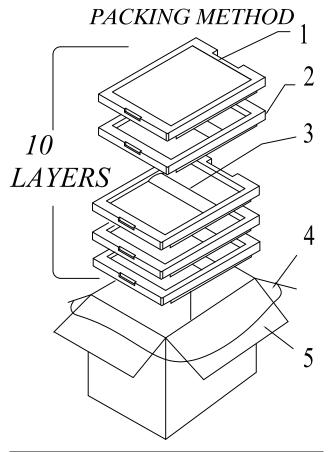
NOTES:

- NOTES: 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994. 2. CONTROLLING DIMENSION: MILLIMETERS. 3. LEADING EDGE OF THE APPROACH ANGLE ON THE GLASS IS LOWER THAN THE TOP OF THE HOUSING. 4. BORE DEPTH IS 6.0 WITH A 0.2 LEAD-IN CHAMFER. 5. PIN HEADER, MODEL NUMBER EBW-PK23-P010L2-3Z, 1X10 PIN, DIVIDUATE
- PITCH 1.25. 6. GLASS IS GLUED ON ALL 4 SIDES.

- GLASS IS GLUED ON ALL 4 SIDES.
  GLASS THICKNESS IS 1.85.
  USE M2.3 SELF TAPPING SCREWS FOR MOUNTING. TORQUE SCREWS BETWEEN 1.80 KGF-CM AND 2.00 KGF-CM.
  DIMENSION DI DENOTES THE SCAN LENGTH.
  DIMENSION K DENOTES THE POSITION OF THE FIRST PIXEL.

	MILLIMETERS		
DIM	MIN	MAX	
Α	13.00	14.00	
A1	6.70	7.70	
A2	13.20	14.20	
В	17.70	18.30	
B1	18.70	19.30	
B2	5.50	6.50	
С	15.20	15.80	
D	119.20	120.20	
D1	104.0	0 REF	
Е	2.10	2.30	
Н	34.80	35.80	
J	5.70	6.30	
К	6.00	8.00	
L	6.00 REF		

# PACKING DIMENSIONS



# 410 mm

PACKING COMPLETE

NO.	NAME	MATERIAL
1	Shockproof Pad	EPE
2	Packing Tray	POLYFOAM
3	Conduct Electricity Sheet	PE + CONDUCTIVE SHEET
4	Waterproof Bag	PE
5	Packing Box-Carton	KRAFT PAPER

The products described herein (NOM02A6-AW49G), is covered by one or more of the following U.S. patent; 6,025,935. There may be other patents pending.

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